

VERSION SHOWING AMENDMENTS TO THE CLAIMS

This listing replaces all prior listings of the claims.

Claims:

1 (Amended) An organic electronic component including a lower layer having a top surface with a spacing I between two adjacent conductor tracks, two adjacent electrodes and /or between a conductor track and an electrode of less than 10 µm in the lower layer, wherein at least one conductor track and/or electrode is arranged in a recess of a the lower layer, wherein the recess was is produced by means of a layer laser, that is to say it has the recess having relatively steep side walls generally perpendicular to the top surface and a bottom surface, the recess exhibiting relatively sharp contours at the junction of the side walls with the bottom recess surface and with the lower layer top surface and a relatively rough bottom surface as compared to the top surface of the lower layer.

2. (Amended) A process for the production of an organic electronic component including a substrate or lower layer having a top surface, in which to produce the process for producing a conductor track and/or an electrode in the substrate or lower layer by burning at least one recess is burnt into the a lower layer or into the substrate by means of emitting a laser beam through a and mask, wherein said recess has a bottom surface and relatively steep walls relative to the top surface, the recess exhibiting relatively sharp contours between the side walls and bottom surface and

between the side walls and the top surface and a rough surface at the bottom surface
as compared to the top surface, and then filling the recess in a subsequent process step
is filled with conductive, predominantly organic material.

3. (Original) A process as set forth in claim 2 wherein the conductive material is scraped into the recess.
4. (Original) A process as set forth in one of claims 2 and 3 wherein excess conductive organic material is wiped away in a process step following the step of filling the recess with said material.
- 5 (Amended) A process as set forth in one of claims 2 through [[4]] 3 wherein the laser is a pulsed laser, for example an excimer laser is used.
6. (Amended) A process as set forth in one of claims 2 through 5 3 which is performed in a continuous roll-to-roll procedure.
7. (Amended) A process as set forth in claim 6 wherein the roll-to-roll procedure including pressing or guiding the substrate or lower layer with pressing or guide rollers and wiping ~~the roller which wipes~~ off the excess organic material from the top surface with a wiping roller, the wiping roller rotating rotates more slowly than the other pressing

or guide rollers.

ADD THE FOLLOWING CLAIM:

8 (New) The process as set forth in one of claims 2 and 3 wherein the laser is an excimer laser.